



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Sun et al.

Attorney Docket No.: EICCP005X1

Application No.: 10/061,546

Examiner: Norris, Jeremy C.

Filed: February 1, 2002

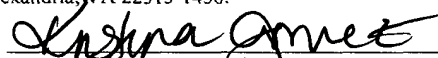
Group: 2827

Title: MULTI-LAYER INTERCONNECT
MODULE AND METHOD OF
INTERCONNECTION

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on September 10, 2003 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: _____


Kristina Gomez


SUBMISSION OF FORMAL DRAWINGS

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Applicant(s) hereby submit Formal Drawings for the above-identified application. If the Draftsman has any question concerning these drawings, he or she is respectfully requested to contact the undersigned.

Respectfully submitted,
BEYER WEAVER & THOMAS, LLP


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